PCB Production Process Technology Explain

1. Common Info

1.0	Main Linkman:	丁朝阳	Phone: 13927497578
	E-mail:	zhaoyang.ding@hanputek.com	Fax:
1.1	Other linkmen:	kangming.dai@hampoo.com	
	Please send EQ confirming order to main linkman, and copy to all others!		

2. Technology Information

2.0	Board Name:	11kw_motor_drive_main-REVB	Board Type: Common Rigid Board
2.1	Layer Count:	6 Layers	Min Via Stagger(mm):0.3048
2.2	Base Material:	FR4	Via Density(one/square metre): 24300.99
2.3	Aspect Ratio:	7:1	Min. Line Width/Spacing(mil):12.00/10.00
	Warpage:	<=0.75%	
2.4	Unit Size(mm):	146.00 X 146.00	Panel Mode: 1 X 1
	Set Size(mm):		Cell Count: 1 Single board types of panel: 1
	☐ V-CUT		
2.5	Board Thickness(mm): 2		Tolerance:± 10%
2.6	Soldermask:	both_sides	Color: Green Mill Finish: Polished
2.7	Refdes:	both_sides	Color: White
	Mark:	☑ UL	Mark Layer: Silk Top
	Don not put factory logo in the blank space of this board.		
	Please put manufacturing date in the blank space of this board.		
2.8	Surface Finish: Immersion Gold	Gold Thick: >=0.05um	Gold Finger: ☑ No ☐ Yes, Gold Thick:
	Gold Finger Bevel:	☐ Yes ☑ No	
	Cut Thin:	☐ Yes ☑ No	
2.9	Via Soldermask Dispose Process:	☐ All vias should be plugged except the vias on pad	
	☐ All vias according to design	☑ All vias need to be plugged.	
	☐ Vias under BGA should be plugged, Other vias according to design		Stuff matter: Printing ink
2.10	Impedance Control:	☐ Yes	☑ No
2.11	HDI:	☐ Yes	☑ No
2.12	Inspection & Acceptance Criteria:	☑ IPC-6012-II, current revision.	
2.13	IPC Netlist Comparison:	☑ Yes	☐ No
2.14	Delivery Accessory:	☑ Electrical Test Report	☑ Deliver Test Report ☑ Gerber
		☑ PCB Micro Section Report(Minimum Via & All Layers Copper Position)	
		☐ Impedance Test Report	☐ Other
2.15	Package Requirements:	☑ Vacuum Package	☑ Fill In The Gap With Paper

3. Layer Stack Setup

REFERENCE LAYER STACKUP (Unit:mils)